



# IC Packaging Markets

## 2013 Global Report Series

With annual shipment around 200 billion units, the complex IC packaging market requires extensive analysis. To provide this analysis **New Venture Research (NVR)** offers four reports for covering the IC packaging market.

The first report, **The Worldwide IC Packaging Market - 2013 Edition**, presents NVR's annual forecast for each of the major package families by semiconductor device type (2011-2017). This report also presents NVR's continuing, extensive coverage of the OSAT market.

The second report, **IC Package Pitch, Leadframe Plating, and Substrate Markets - 2013 Edition**, forecasts the pitch for all major IC package families by I/O count ranges, as well as forecasts of plating options for the leadframes.

Lead-free issues also discussed. Substrate forecasts also included. Forecasts are for years 2012 - 2017.

The third report, **The Array IC Packaging Market - 2013 Edition**, analyzes the market for BGAs/LGAs, FBGAs/FLGAs, and WLP packages including Fan-Out WLP, plus Fan-In or Multi-Row QFN. Forecasts are for years 2012 - 2017.

The fourth report, **The Multi-Component IC Packaging Market - 2013 Edition**, analyzes stacked packages, SiPs, and through-via technologies over the next five years. Forecasts are for years 2011 - 2017.

These IC packaging reports provide the most comprehensive analysis available today on the IC packaging markets (more details are provided on the next page).

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Chapter 1: Introduction

Chapter 2: Executive Summary

Chapter 3: The Economic State of the Industry

Chapter 4: IC Package Forecast by Device Type

Chapter 5: IC Package Forecast by Package Family

Chapter 6: Packaging Contractor Market

Chapter 7: OSAT Profiles

Publish date, May 2013 - 425 pages

## Report 2: IC Package Pitch, Leadframe Plating, and Substrate Markets - 2013 Edition

Chapter 1: Introduction

Chapter 2: Executive Summary

Chapter 3: The Economic State  
of the Industry

Chapter 4: Pitch by Major Package Family and I/O Count Range

Chapter 5: Leadframe Plating Options and Lead-free Issues

Chapter 6: Substrates

Publish date, August 2013 - 200 pages

## Report 3: The Array IC Packaging Market - 2013 Edition

Chapter 1: Introduction

Chapter 2: Executive Summary

Chapter 3: The Economic State of the Industry

Chapter 4: BGA/LGA By I/O Count and Device Type

Chapter 5: FBGA / FLGA

By I/O Count and Device Type

Chapter 6: WLP—including Fan-Out

Chapter 7: QFN—including Fan-In or Multi-Row

Publish date, October 2013 - 110 pages

## Report 4: The Multi-Component IC Packaging Market - 2013 Edition

Chapter 1: Introduction

Chapter 2: Executive Summary

Chapter 3: The Economic State of the Industry

Chapter 4: Stacked Packages

Chapter 5: SiPs

Chapter 6: Through-Via Technology

Publish date, December 2013 - 175 pages

## About the Author

**Sandra L Winkler** has been an industry analyst since 1988, and has authored many off-the-shelf as well as custom market research reports. Ms. Winkler began her analyst career in the telecommunications industry, with **Frost and Sullivan** but evolved to the semiconductor packaging industry as of 1995. She is the author of more than 30 reports for **NVR** on this and other topics, including *The Worldwide IC Packaging Market*, *Advanced IC Packaging Markets and Trends*, and *IC Packaging Materials*. She is widely published in *Chip Scale Review*, *Global SMT & Packaging News*, and contributes to the **IEEE/CPMT** newsletter and other print media. Ms. Winkler holds an MBA from Santa Clara University and is on the executive planning committee of the **IEEE/CPMT**, Santa Clara Valley chapter.